



Material Content Data Sheet



Sales Product Name		BFP 640F H6327		Issued		27. September 2017		
MA#		MA000895776						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.03		269	
	noble metal	gold	7440-57-5	0.002	0.10		1041	
	inorganic material	silicon	7440-21-3	0.017	0.91	1.04	9075	10385
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		395	
	non noble metal	chromium	7440-47-3	0.002	0.12		1184	
	non noble metal	copper	7440-50-8	0.734	39.29	39.46	392928	394586
wire	noble metal	gold	7440-57-5	0.007	0.35	0.35	3529	3529
	encapsulation	organic material	carbon black	0.010	0.52		5168	
encapsulation	plastics	epoxy resin	-	0.208	11.11		111112	
	inorganic material	silicondioxide	60676-86-0	0.749	40.05	51.68	400520	516800
	leadfinish	non noble metal	tin	0.050	2.65	2.65	26521	26521
plating	noble metal	silver	7440-22-4	0.090	4.82	4.82	48179	48179
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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